

Plasma Polishing Technology

Traditional polishing process

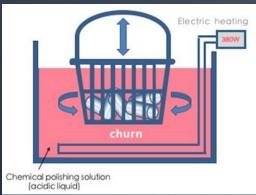


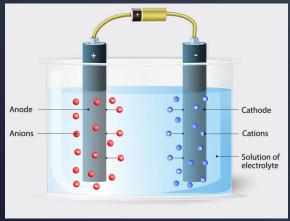
- Mechanical polishing
 - Polish the metal surface by mechanical tools

- Chemical polishing
 - Polish the metal surface by chemical reaction

- **■** Electrochemical polishing
 - Polish the metal surface by anodic dissolving







Limitations of traditional polishing process



Mechanical polishing

- Simple objects
- Labor intensive/low efficiency
- Dust explosion

Chemical polishing

- Poor uniformity of the gloss
- Fire hazard
- Expensive post-treatment of chemical solutions

Electrochemical polishing

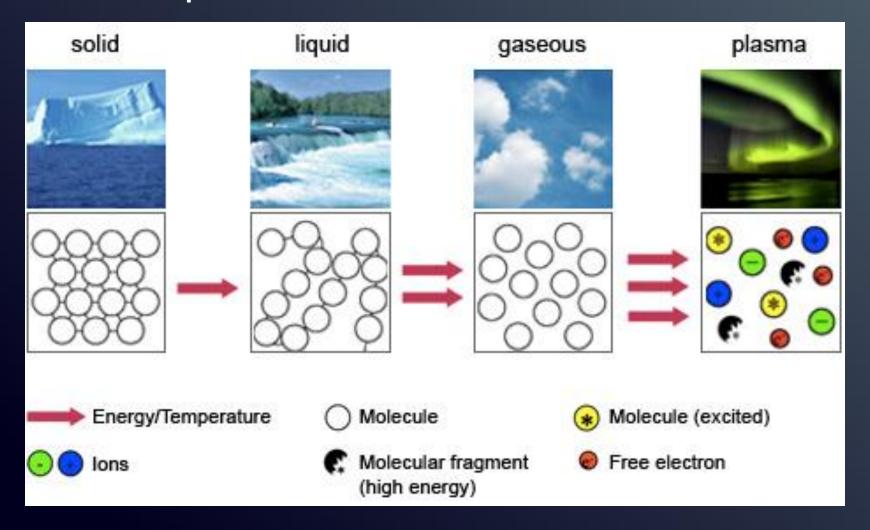
- Corrosion of the polishing machines
- Expensive post-treatment of polishing solutions
- Poor dimensional tolerance







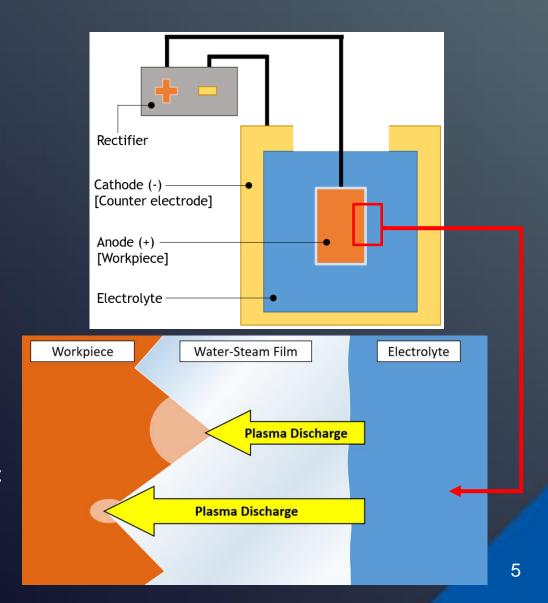
What is plasma



Design of multi-stage plasma polishing process hkpc

Operation process

- **1**st
 - Pre-treatment of the metallic object
- 2nd
 - Immerse the metallic object into the polishing solution
- 3rd
 - Gas film formed on the surface of the metallic object under high voltage
 - Plasma discharged on the surface of the metallic object



Design of multi-stage plasma polishing process hkpc

- Plasma polishing machine
- Rectifier
 - **Provide high voltage**
- Adjustable cathode
 - Distance-adjustable octagonal cathode
- Anode with workpiece fixer
 - Fix the metallic object on the anode
- Polishing tank
 - Excellent chemical and thermal stability
- Washing tank
 - Post-treatment of metallic object





Parameters of the plasma polishing process

- Parameters
- Applied voltage: 300~600V
- Temperature of the polishing solution: 50-80 °C
- Polishing time: 1-6 min
- Material of the metallic object: metal or metal alloy
- pH of the polishing solution: 5-7
- Distance between electrodes: 1-10 cm
- Area ratio of metallic object and cathode: 1:1 to 1:50



Advantages of plasma polishing process

- Automatic polishing process
- Uniform roughness and gloss
- High dimensional tolerance
- Dust explosion
- No toxic solution and waste





1/14/2021

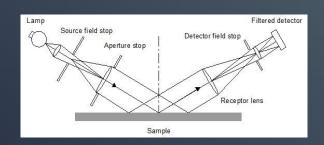


Material Characterization Method hkpc



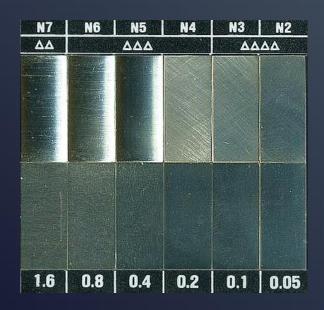
Glossmeter

 Gloss is an optical property which indicates how well a surface reflects light in a specular (mirror-like, >600 GU) direction.



Morphology

 The morphology of a surface is characterized by an optical microscope with a digital camera.

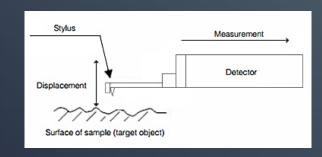


Material Characterization Method hkpc hkpc



Roughness meter

 Roughness is the average of vertical deviations from nominal surface over a specified length surface.





Stylus Profilometer



Optical Profilometer



Plasma polishing of stainless steel (SS)



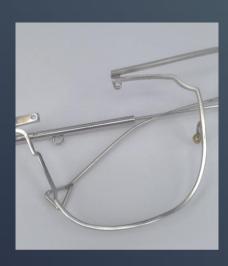
Watch bracelet



Watch case



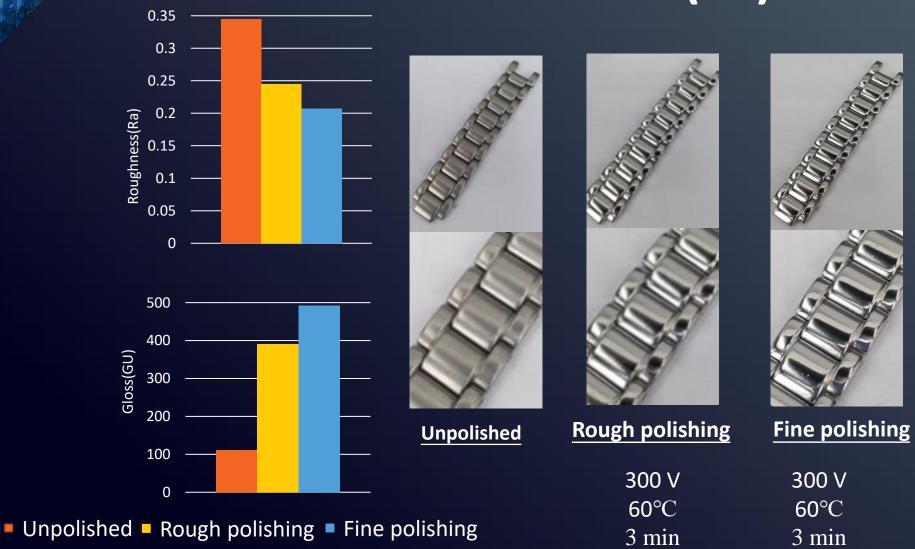
Watch clasp



Glasses

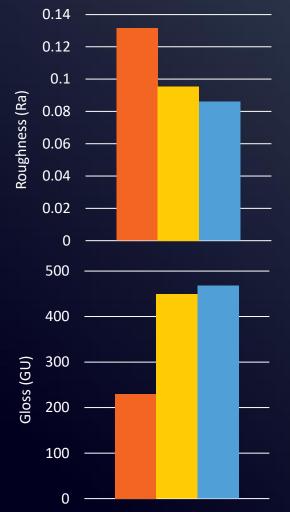
Plasma polishing results of watch bracelet (SS)

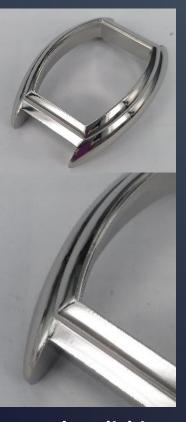




Plasma polishing results of watch case (SS)









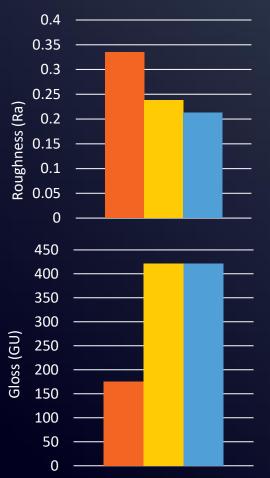
Unpolished

Rough polishing
300 V
60°C
3 min

Fine polishing
400 V
80°C
3 min

Plasma polishing results of watch clasp (SS)





Unpolished



Rough polishing 300 V 60°C

3 min



Fine polishing 300 V 80°C 3 min

Plasma polishing results of glasses (SS)



Polishing condition: 300 V 80°C 2 min



Unpolished



Fine polishing



Unpolished

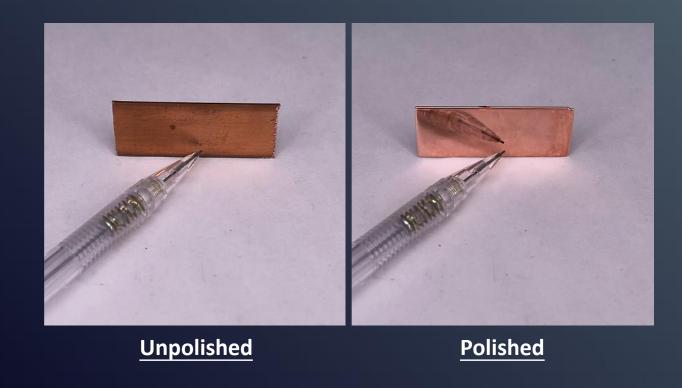
Fine polishing

Plasma polishing of Copper sample



Polishing condition: 300 V 80°C 3 min





Plasma polishing of Titanium (Ti)



Polishing condition: 550 V 85°C 1 min



Summary



	Traditional polishing process	Plasma polishing process
Polishing time	> 10 minutes	1-6 minutes
Simple process	No	Yes
Labor-intensive	Yes	No
Removal of material	More	Less
Post-treatment of polishing solution	Yes	No
Environmental-friendly	No	Yes



Daniel Wong 黃鯤鵬 Consultant 顧問 Smart Manufacturing智能製造 Email: danielkpwong@hkpc.org T: (852) 2788 5509



Q&A



Hong Kong Productivity Council 香港生產力促進局

HKPC Building, 78 Tat Chee Avenue, Kowloon, Hong Kong 香港九龍達之路78號生產力大樓 +852 2788 5678 www.hkpc.org